

**THIS  
CHANGES  
ALL**

SWISS MADE  
**INDEOtec**  
PLASMA PROCESS EQUIPMENT

proudly unveils

# Octopus

with  
Mirror Reactor

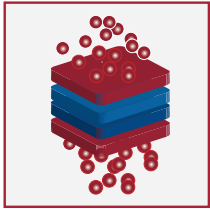
A real innovation in PECVD  
RF- and VHF-deposition technology

- Top & bottom thin film deposition in successive reactors without vacuum breakage or substrate flipping
- Special bifacial carrier plate hole design for minimized substrate edge bearing
- Secondary compensation electrode for excellent film thickness uniformity and passivation quality levels

IDEAL FOR

PV cell coatings  
Opto-electronic layers  
MEMS/semicon devices





2-sided deposition  
is **simple** now

- RF deposition at top & bottom side in one system
- Excellent results for a-Si:H layers (intrinsic, doped), SiO<sub>x</sub>, SiN<sub>x</sub>
- NO substrate flipping
- NO vacuum breakage

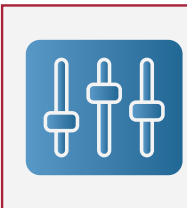
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Cut operation costs  
Cut footprint

- Drastically reduced handling steps reduce risk of breakage
- Elimination of intermediate vacuum breakage cuts costs
- Substantial footprint savings by smart platform design



Regulate your  
layer profile

- Customization of film thickness profile possible
- Adaption of film profile to slightly bended substrates
- NO change of plasma or stoichiometry



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